12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20120517001
Qualification of JCAP as an Additional Assembly, Bump, and Test site for the TPS62650YFFR/T and TPS62651YFFR/T Devices
Change Notification / Sample Request

Date: 6/1/2012
To: Newark PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120517001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS62651YFFT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20120517001	**PCN Date:**	06/01/2012

Title:	Qualification of JCAP as an Additional Assembly, Bump, and Test site for the TPS62650YFFR/T and TPS62651YFFR/T Devices

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	09/01/2012	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Qualification of JCAP as an Additional Assembly, Bump, and Test site for the TPS62650YFFR/T and TPS62651YFFR/T Devices. Current site is in TI-Clark. Assembly differences are shown in the following table:

	Clark-AT	**JCAP-AT**
Bump Site	Clark-BP	JCAP-FAB
Solder Ball	4207848	MA22008110

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
Clark-AT	Assembly Site Origin (22L)	ASO: QAB
JCAP-AT	Assembly Site Origin (22L)	ASO: JCP

Sample product shipping label to show code location only - not actual product label

TEXAS INSTRUMENTS
MADE IN: Philippines
2DC: 2Q:
MSL 3 /260C/168 HR | SEAL DT 10/11/11
G1
OPT:
ITEM: 030DB107CMR-Q& 19
LBL: 1A (L)TO:1168
(1P) PTWL6030DB107CMR
(Q) 1908 (D) 1136
(31T) LOT: 1606673PHI
(4W) SWR (1T) 8550440Z48
(P)
(2P) REV: A (V) 0033317
(20L) CSO: RFB (21L) CCO: USA
(22L) ASO: PHI (23L) ACO: PHL

Assembly Site Code: Clark-AT=I, JCAP-AT=P

Product Affected:			
TPS62650YFFR	TPS62650YFFT	TPS62651YFFR	TPS62651YFFT

Qualification Plan

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: TPS62651YFFR (MSL1-260C)

Qualification Schedule:	**Start:**	June 2012	**End:**	August 2012

Package Construction Details

Assembly & Bump Site:	JCAP	**Bump Composition:**	SnAgCu
# Pins-Designator, Family:	6-YFF, WCSP/DSBGA	**Bump Diameter:**	0.25mm

Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test	Conditions	Sample Size/Fail
		Lot#1
Electrical Characterization	--	5/0
Manufacturability (Assembly)	(per mfg. Site specification)	1/0
BUMP MQ	(per mfg Site specification)	1/0

Notes: ** Tests require preconditioning sequence: MSL1-260C

Reference Qualification:

Qualification Plan

Qual Vehicle: TPS2025YFF (MSL1-260C)

Qualification Schedule:	**Start:**	May 2012	**End:**	July 2012

Package Construction Details

Assembly & Bump Site:	JCAP	**Bump Composition:**	SnAgCu
# Pins-Designator, Family:	6-YFF, WCSP/DSBGA	**Bump Diameter:**	0.25mm

Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test	Conditions	Sample Size/Fail	
		Lot#1	**Lot#2**
Electrical Characterization	--	10/0	--
**High Temp. Storage Bake	170C (420hrs)	45/0	--
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0	--
**Temperature Cycle	-55C/+125C (1000 Cyc)	77/0	--
Physical Dimensions	(per mechanical drawing)	5/0	--
Manufacturability (Assembly)	(per mfg site specifications)	1/0	--
Backgrinding Characterization	(per mfg site specifications)	1/0	--
BLR TC	-40/125C, 200, 500, 750, 1000 cycles	32/0	--

** - Test requires Moisture Preconditioning (MSL1-260C)

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com